

NOTES:

1. MATERIAL:
  - 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:BLACK.
  - 1.2 CONTACT: COPPER ALLOY.
  - 1.3 FITTING NAIL: COPPER ALLOY.
2. FINISH:
  - 2.1 CONTACT:
    - GOLD FLASH PLATING(1~3u") ON CONTACT AREA.
    - 100~200u" TIN PLATING ON SOLDER TAILS,
    - 50~100u" NICKEL UNDERPLATING OVERALL.
  - 2.2 FITTING NAIL:
    - 100~200u" TIN PLATING ON SOLDER TAILS.
    - 50~100u" NICKEL UNDERPLATING OVERALL.
3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
4. SPEC. PLS. REFER TO PS-50226-xxxx-xxx
5. PACKAGE PLS. REFER TO 88047-XXXX-TRP
6. PART NUMBER

P/N LEGEND

50226-XXX X X-XXX

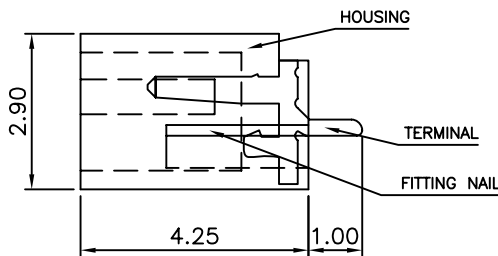
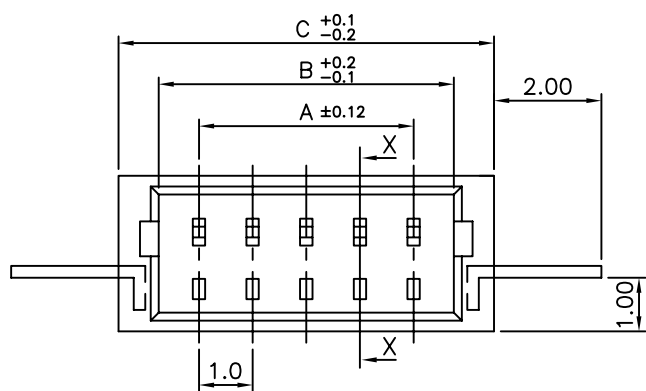
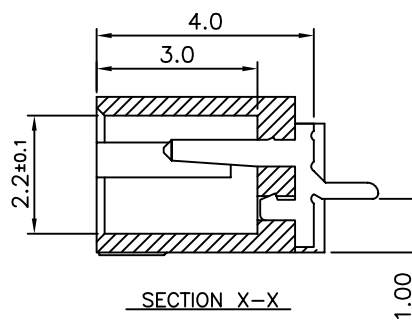
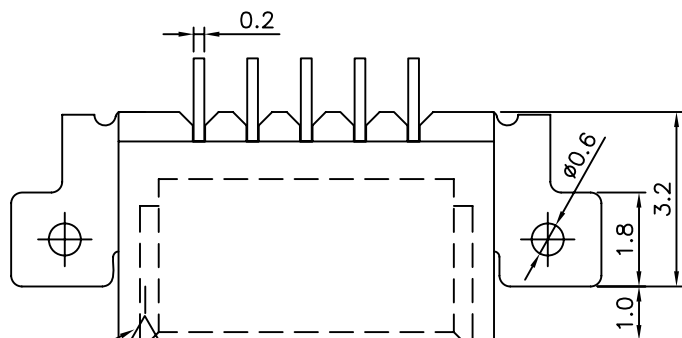
No Of CKT

XXX	Housing Color
001	Black

Plating  
L:Lead Free(Pure Tin)  
1:Gold Flash over all

Packing  
0:Tape & Reel  
1:Tube Package

CKT	DIM A	DIM B	DIM C
2	1.0	2.4	4.0
3	2.0	3.4	5.0
4	3.0	4.4	6.0
5	4.0	5.4	7.0
6	5.0	6.4	8.0
7	6.0	7.4	9.0
8	7.0	8.4	10.0
9	8.0	9.4	11.0
10	9.0	10.4	12.0
11	10.0	11.4	13.0
12	11.0	12.4	14.0
13	12.0	13.4	15.0
14	13.0	14.4	16.0
15	14.0	15.4	17.0
16	15.0	16.4	18.0
17	16.0	17.4	19.0
18	17.0	18.4	20.0
19	18.0	19.4	21.0
20	19.0	20.4	22.0
22	21.0	22.4	24.0



REV	REVISION DESCRIPTION	DATE	SIGNATURE
A	修改SPEC	'08/12/29	liuwei
O	NEW DRAWING	'08/10/14	liuwei

一般公差 <b>TOLERANCES</b> X ±0.5 XX ±0.15 X ±0.25 XXX ±0.1 ANGLES ±2°		<b>宏致電子股份有限公司</b> <b>Aces Electronic Co.,Ltd.</b>	
檢驗尺寸標示 <b>SYMBOLS</b> ⊕ ⊕ INDICATE CLASSIFICATION DIMENSION ⊕ MARK IS CRITICAL DIM. ⊕ MARK IS MAJOR DIM.	品名 (TITLE) 0.8mm WTB S/R WAFER SMT R/A 圖號 (DWG.NO) <b>50226-XXXXX-XXX</b>	製圖 (DR) '08/10/14 liuwei 審核 (CHKD) Sam 核准 (APPD) Jason	張數 (SHEET) 1 OF 1 比例 (SCALE) 8:1 單位 (UNITS) mm
表面處理 (FINISH)		圖號 (DWG.NO)	